



#### **Features**

- 4-Pin SMD package
- Fast warm-up
- Frequency Range, 10 MHz to 40 MHz
- Standard freq: 10, 12.8, 20, 24.576, 25, 30.72 MHz,
- High Relability (based on fully intergrated Design)
- Low Power

#### **Applications**

- Base stations (5G & 4G)
- Test equipment
- Small Cell
- Military communication equipment
- Stratum 3
- SyncE; 1588

Frequency Stabilities <sup>1</sup> 10 to 40 MHz						
Parameter	F Min	requency S Typical	Max	Units	z Condition	
vs. operating temperature range (referenced to +25°C)	-20 -10 -20		+20 +10 +20	ppb ppb ppb	-40 to +85°C -40 to +85°C -40 to +95°C	Options <sup>5</sup>
slope	-2		+2	ppb/°C	@ Temp stab. +-10ppb	
Initial tolerance vs. supply voltage change vs. load change vs. aging / day vs. aging / year vs. aging / 10 years	-0.5 -10 -5 500 -3	±3 ±2 ±2	+0.5 +10 +10 +5 +500 3	ppm ppb ppb ppb ppb ppm	at time of shipment, nominal EFC V <sub>s</sub> ±5% static Load ±5% static after 30 days of operation after 30 days of operation after 30 days of operation	
Holdover drift			5	ppb	over 24 hours, constant temperature (<±1 after 30 days continous opperation	°C) ;
Start up time			200	msec		
Warm-up time			3	minutes	to ±50ppb of final frequency (1 hour readi @ +25℃	ing)
Loop bandwith for wander generation compliance	3			mHz	MTIE compliant with GR-1244 Fig 5-5 TDEV compliant with GR- 1244 Fig 5-4 measurement setup: oscillator stabilized hours at Constant Temperature (±1°C, st air), data collected over 100,000 seconds a second intervals (-3dB cutoff, 1st order hi pass loop filter)	; 24 till at 1

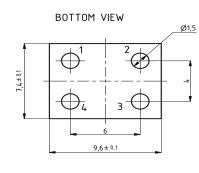
**Performance Specifications** 

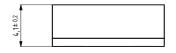
# **Performance Specifications**

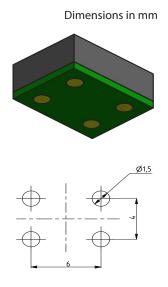
Supply Voltage (Vs)						
Parameter	Min	Typical	Max	Units	Condition	
Supply voltage (standard)	3.135	3.3	3.465	VDC		
Devergencymentics		1.3	1.5	Watts	during warm-up	
Power consumption		0.4	0.5	Watts	steady state @ +25°C	
			RF Outpu	t		
Signal [standard]		LVHC	CMOS			
Load		15		рF		
Signal Level (Vol)			0.4	VDC	with Vs=3.3V and 15pF Load	
Signal Level (Voh)	2.97	3.3		VDC	with Vs=3.3V and 15pF Load	
Duty Cycle	45		55	%	@ (Voh-Vol)/2	
Ron		26.5		Ω		
Roff		22		Ω		
		Frequ	uency Tunir	ng (EFC)		
Tuning Range		Fixed OCX	D; No adjust			
Additional Parameters						
Phase Noise <sup>3</sup>		-99 -125 -145 -155 -160	-90 -120 -140 150 -155	dBc/Hz dBc/Hz dBc/Hz dBc/Hz dBc/Hz	10 Hz 100 Hz 1 kHz @ 20M 10 kHz 100kHz	ИНz
Weight			1.0	g		
Processing & Packing	Processing & Packing Handling & Processing Note					
		Absolu	te Maximui	m Ratings		
Supply voltage (Vs)			3.8	V	with Vs=3.3 VDC	
Output Load			50	pF		
Operable Temperature Range	-40		+95	°C		
Storage Temperature Range	-40		+125	°C		

# **Outline Drawing / Enclosure**

G349





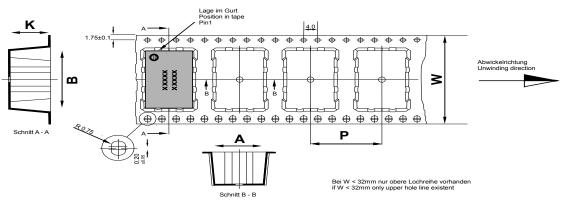


OX-601Height "H"cover material4.1plastic

Pin Connections			
1	I.C (Do not connect) / EFC (option)		
2	Ground (Case)		
3	RF Output		
4	Supply Voltage Input		

Recommended Pad Layout

# Standard Shipping Method (OX-601)



Maßangaben in mm:	Dimension in mm:
A, B und K Maße von Bauelement abhängig	A, B und K are dependent uppon component dimensions
Fertigungstoleranzen entsprechen der DIN IEC 286-3	production tolerance complying DIN IEC 286-3

All dimensions in millimeters unless otherwise stated

Enclosure Type	Tape Width W (mm)	Quantity per meter	Quantity per reel	Dimension P
OX-601 (4.1 mm)	24	83.3	850	12

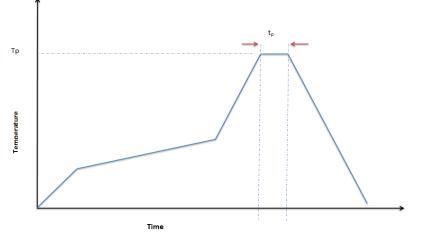
## **Reflow Profile**

TP: max 250°C (@ solder joint, customer board level) Tp: max: 10...40 sec

Additional Information:

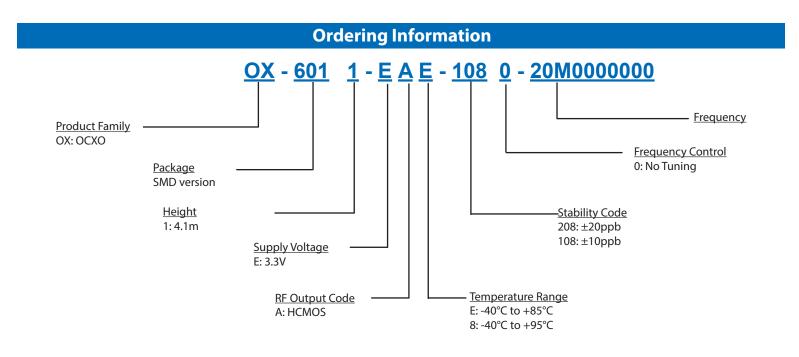
This SMD oscillator has been designed for pick and place reflow soldering

SMD oscillators must be on the top side of the PCB during the reflow process.



## **Additional Environmental Conditions**

Parameter	Description
Temperature Cycling	JESD22-A104-D Cond.G - 500cycles -40/+125C;cycle time 30min
Vibration, Sine	MIL-STD-883 Meth 2007 Cond A - 20g 20-2000Hz 4x in each 3 axis 4min sweep time
Mechanical Shock	MIL-STD-202 Meth 213B Cond. F - 1500g 0,5ms 6 shocks in each direction
Solderability	J-STD-002C Cond. A, Trough hole device; Cond.B, SMD ( correspond to MIL-STD-883 Meth 2003) - 255C (diving Time 5 0,5sec.) Dip&Look with 8h damp pre-treatment: solder wetting >95%
Solvent resistance	MIL-STD-883 Meth 2003) - 255C (diving Time 5 0,5sec.) Dip&Look with
ESD	8h damp pre-treatment: solder wetting >95%
Moisture Sensit.	JESD22-A113-B - only if > MSL 1
RoHS compliance	100% RoHS 6 compliant
Washable	non-washable device
High temp operating life(HTOL)	MIL-STD-202 Meth108A Cond C - 1000h @ 105C power on
Low temp operating life(LTOL)	IEC 60068-2-1 Cond. Ae - 1000h @ -40C power on



#### Notes:

- 1. Contact factory for improved stabilities or additional product options. Not all options and codes are available at all frequencies.
- 2. Unless other stated all values are valid after warm-up time and refer to typical conditions for supply voltage, frequency control voltage, load, temperature (25°C).
- 3. Phase noise degrades with increasing output frequency.
- 4. Subject to technical modification.
- 5. Contact factory for availability.

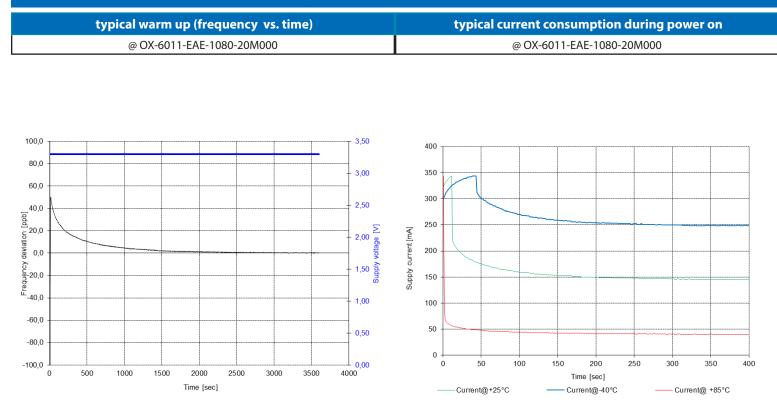


Microsemi Headquarters One Enterprise, Aliso Viejo, CA 92656 USA Within the USA: +1 (800) 713-4113 Outside the USA: +1 (949) 380-6100 Sales: +1 (949) 380-6136 Fax: +1 (949) 215-4996 email: sales.support@microsemi.com www.microsemi.com Microsemi, a wholly owned subsidiary of Microchip Technology Inc. (Nasdaq: MCHP), offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions, security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Learn more at www.microsemi.com.

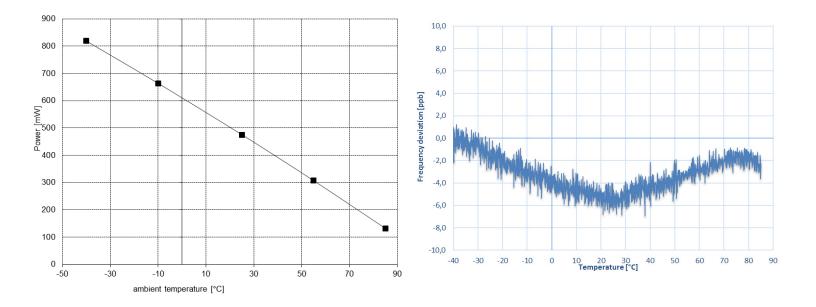
Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever ansing out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or performance and verify the same. The information provided by Microsemi hereunder is provided by Microsemi, it is the Buyer's responsibility to independently determine subtability of any products and torefy the same. The information provided by Microsemi any other/IP information, thereard to any other IP information. For mation provided by Microsemi any other IP information, see the regard to such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party and information. Information information. Information provided by usen information. Information revised to such and performance and performance and Microsemi does not grant, explicitly or implicitly, to any party and information. Information information. Information revised to such information. Information revised to such and any other IP information. Information and set of any products and services at any time without notice.

©2018 Microsemi, a wholly owned subsidiary of Microchip Technology Inc. All rights reserved. Microsemi and the Microsemi logo are registered trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners.

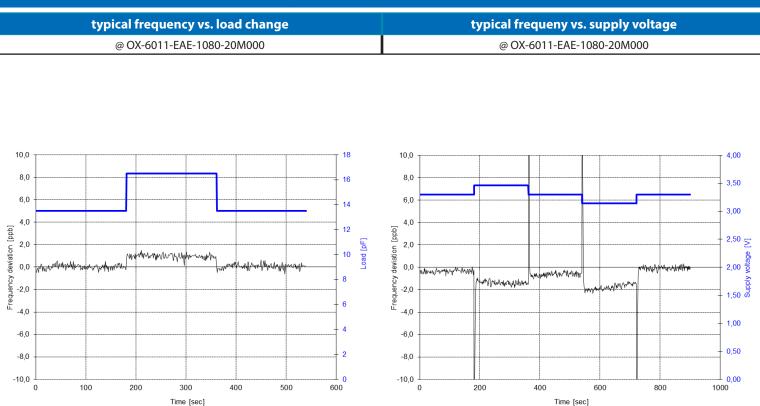
## typical perforamce data



typical power consumption vs. operating temperauture	typical frequency vs. temperature stability
@ OX-6011-EAE-1080-20M000	@ OX-6011-EAE-1080-20M000



## typical perforamce data



typical frequency. vs cycled airflow without additional cover	typical frequency. vs cycled airflow with additional cover
@ OX-6011-EAE-1080-20M000	@ OX-6011-EAE-1080-20M000

